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| Orderable: ChangeMe! | Designed for: Public Release | Mod. Date: 12/8/2017 |
| TID #: N/A | Project Title: High Efficiency, High Power Density Active Clamp Flyback | |
| Number: PMP40328 | Rev: E1 | Sheet Title: |
| SVN Rev: Version control disabled | Assembly Variant: 001 | Sheet: 1 of 1 |
| Drawn By: | File: PMP40328_BlankSheet.SchDoc | Size: B |
| Engineer: David Ji | Contact: http://www.ti.com/support | |



Reference

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